

EAST - [capacitor to via.wsp:1]										
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BRS form IS&R form Image Text										
	U	I	Document ID	Iss	Page	Title	Current OR	Current XRef	Retrieval Classif	Inve
1	<input type="checkbox"/>	<input type="checkbox"/>	US 6225683 B1	200	16	Die size-increasing integrated circuit leads and thermally enhanced	257/666	257/692 : 257/696 : 257/783		Yalamanchili, Pra , et al.
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6201297 B1	200	36	Semiconductor device	257/690			Masuda, Masachi
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6198163 B1	200	12	Thin leadframe-type semiconductor package having heat sink with recess and	257/706	257/675 : 257/707 : 257/712		Crowley, Sean Tir , et al.
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5982043 A	199	8	Semiconductor device having two or more bonding option pads	257/786	257/690 : 257/691 : 257/695		Iwata, Katsutoshi
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5942794 A	199	25	Plastic encapsulated semiconductor device and method of manufacturing	257/666	257/693 : 257/787		Okumura, Ichiro , et al.
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5929514 A	199	15	Thermally enhanced lead-under-paddle I.C. leadframe	257/676	257/666 : 257/675 : 257/692		Yalamanchili, Pra
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5608265 A	199	18	Encapsulated semiconductor device package having holes for electrically	257/738	257/685 : 257/686 : 257/737		Kitano, Makoto , et al.
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5468991 A	199	6	Lead frame having dummy leads	257/666	257/675		Lee, Joon K. , et al.
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5428247 A	199	12	Down-bonded lead-on-chip type semiconductor device	257/676	257/664 : 257/666 : 257/668		Sohn, Hal-jeong , et al.
10	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5389817 A	199	9	Semiconductor device having a flat jumper lead	257/666	257/676		Imamura, Tsutom , et al.
11	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5373188 A	199	17	Packaged semiconductor device including multiple semiconductor chips and	257/666	257/773 : 257/776		Michii, Kazunari , et al.
12	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5295045 A	199	14	Plastic-molded-type semiconductor device and producing method therefor	361/813	174/261 : 174/52.1 : 174/52.2		Kitano, Makoto , et al.

COL - good

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	U	1	Document ID	Iss	Page	Title	Current OF	Current XRef	Retrieval Classif	In
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20010008302 A1		71	Semiconductor device				Murakami, Gen, Tsubosaki, Ku, et al.
2	<input type="checkbox"/>	<input type="checkbox"/>	US 6326681 B1	200 112 04	68	Semiconductor device	257/676	257/666 ; 257/787		Murakami, Gen, et al.
3	<input type="checkbox"/>	<input type="checkbox"/>	US 6303982 B1	200 110 16	69	Semiconductor device	257/666	257/659 ; 257/660 ; 257/676		Murakami, Gen, et al.
4	<input type="checkbox"/>	<input type="checkbox"/>	US 6204552 B1	200 103 20	69	Semiconductor device	257/666	257/676		Murakami, Gen, et al.
5	<input type="checkbox"/>	<input type="checkbox"/>	US 6201297 B1	200 103 13	36	Semiconductor device	257/690			Masuda, Masa
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6124629 A	200 009 26	68	Semiconductor device including a resin sealing member which exposes the	257/666	257/676 ; 257/787		Murakami, Gen, et al.
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6100580 A	200 008 08	69	Semiconductor device having all outer leads extending from one side of a	257/666	257/676 ; 257/691		Murakami, Gen, et al.
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6081023 A	200 006 27	69	Semiconductor device	257/666	257/676		Murakami, Gen, et al.
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6072231 A	200 006 06	70	Semiconductor device	257/666	257/668 ; 257/676 ; 257/691		Murakami, Gen, et al.
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5929514 A	199 907 27	15	Thermally enhanced lead-under-paddle I.C. leadframe	257/676	257/666 ; 257/675 ; 257/692		Yalamanchili, I
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5914530 A	199 906 22	68	Semiconductor device	257/666	257/659 ; 257/676		Murakami, Gen, et al.
12	<input type="checkbox"/>	<input type="checkbox"/>	US 5821606 A	199 810 13	69	Semiconductor device	257/666	257/659		Murakami, Gen, et al.

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COL NOT GOOD

no pad used for COL or LOC

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	U	1	Document ID	Iss	Page	Title	Current OR	Current XRef	Retrieval Classif	In
6	<input type="checkbox"/>	<input type="checkbox"/>	US 6124629 A	200 009 26	68	Semiconductor device including a resin sealing member which exposes the	257/666	257/676 ; 257/787		Murakami, Gen , et al.
7	<input type="checkbox"/>	<input type="checkbox"/>	US 6100580 A	200 008 08	69	Semiconductor device having all outer leads extending from one side of a	257/666	257/676 ; 257/691		Murakami, Gen , et al.
8	<input type="checkbox"/>	<input type="checkbox"/>	US 6081023 A	200 006 27	69	Semiconductor device	257/666	257/676		Murakami, Gen , et al.
9	<input type="checkbox"/>	<input type="checkbox"/>	US 6072231 A	200 006 06	70	Semiconductor device	257/666	257/668 ; 257/676 ; 257/691		Murakami, Gen , et al.
10	<input type="checkbox"/>	<input type="checkbox"/>	US 5929514 A	199 907 27	15	Thermally enhanced lead-under-paddle I.C. leadframe	257/676	257/666 ; 257/675 ; 257/692		Yalamanchili, I
11	<input type="checkbox"/>	<input type="checkbox"/>	US 5914530 A	199 906 22	68	Semiconductor device	257/666	257/659 ; 257/676		Murakami, Gen , et al.
12	<input type="checkbox"/>	<input type="checkbox"/>	US 5821606 A	199 810 13	69	Semiconductor device	257/666	257/659		Murakami, Gen , et al.
13	<input type="checkbox"/>	<input type="checkbox"/>	US 5793099 A	199 808 11	68	Semiconductor device	257/666	257/676 ; 257/776		Murakami, Gen , et al.
14	<input type="checkbox"/>	<input type="checkbox"/>	US 5612569 A	199 703 18	67	Semiconductor device	257/666	257/783		Murakami, Gen , et al.
15	<input type="checkbox"/>	<input type="checkbox"/>	US 5530286 A	199 606 25	67	Semiconductor device	257/692	257/666 ; 257/693		Murakami, Gen , et al.
16	<input type="checkbox"/>	<input type="checkbox"/>	US 5313102 A	199 405 17	9	Integrated circuit device having a polyimide moisture barrier coating	257/787	257/666 ; 257/692 ; 257/696		Lim, Thiam B. , et al.
17	<input type="checkbox"/>	<input type="checkbox"/>	US 5164815 A	199 211 17	9	Integrated circuit device and method to prevent cracking during surface	257/666	257/618 ; 257/787		Lim, Thiam B.

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-  UDC

☒ Highlight all hit terms initially

257787.ccls. and (filler and resin)

 BRS I...
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	Inventor	U	I	Document ID	Iss	Page	Title	Current OF	Current XRef	Retrieval Cla
1	Harada, Tadaaki	<input type="checkbox"/>	<input type="checkbox"/>	US 20020043728 A1	200 204 18	19	Resin composition for sealing semiconductor, semiconductor device using the same, semiconductor wafer and	257/787	257/788; 257/795	257/787
2	Sakamoto, Noriaki et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 20020027298 A1	200 203 07	16	Semiconductor device and method of manufacturing the same	257/787	257/781; 257/784; 257/792;	257/787
3	Danno, Tadatashi et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 20020025607 A1	200 202 28	38	Semiconductor device and a method of manufacturing the same	438/126	257/692; 257/787; 438/127;	257/787
4	Kanatake, Mitsuhito	<input type="checkbox"/>	<input type="checkbox"/>	US 20020020923 A1	200 202 21	17	Semiconductor device and manufacturing method thereof	257/778	257/787; 257/790	257/787
5	Kinouchi, Kan et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 20020020910 A1	200 202 21	20	Semiconductor device including bonding wire bonded to electronic part and method for manufacturing the same	257/697	257/701; 257/781; 257/787;	257/787
6	KATO, YOSHITSUGU et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 20010045643 A1	200 111 29	19	SEMICONDUCTOR DEVICE KEEPING STRUCTURAL INTEGRITY UNDER HEAT-GENERATED STRESS	257/706	257/737; 257/787; 438/112;	257/787
7	Kato, Yoshimasa et al.	<input type="checkbox"/>	<input type="checkbox"/>	US 20010018229 A1	200 108	21	Semiconductor device and method for fabricating same	438/106	257/787; 438/114;	257/787

L Number	Hits	Search Text	DB	Time stamp
1	884	(257/668).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/29 11:33
2	289	(257/673).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/29 11:54
3	499	(257/707).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/04/29 11:54